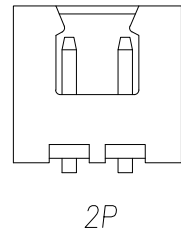
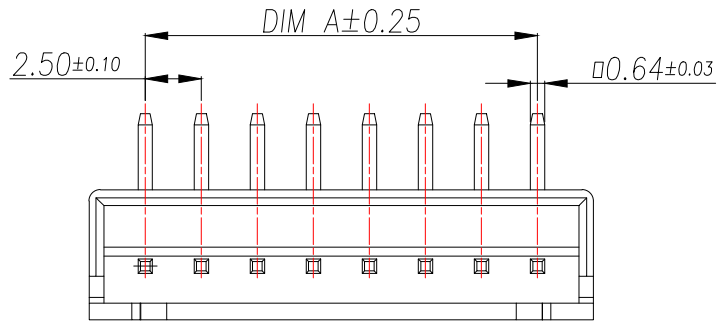


REV.	Q'TY	ECN. NO.	APR.	DATE

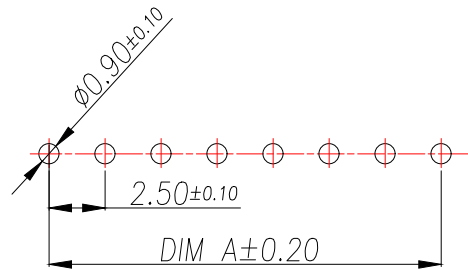
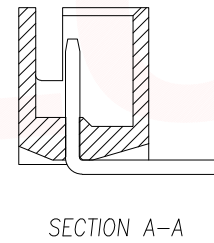
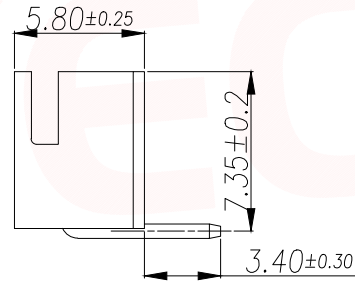
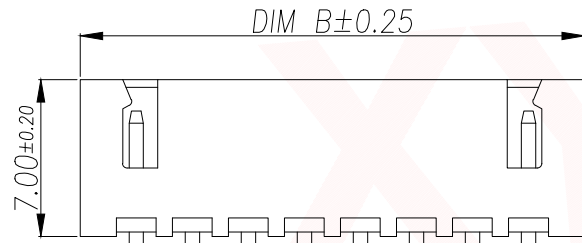


技术要求:

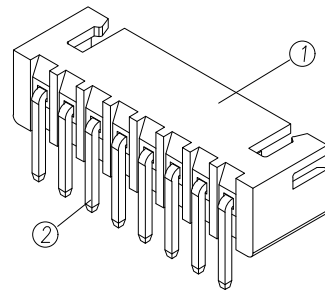
1. 塑件材料: PA66 (UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 1000M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 3.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim +85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235^{\circ}\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求

PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE

Part No	PIN	A	B
XY-XH2.5-2A21	2	2.5	7.5
XY-XH2.5-3A21	3	5.0	10.0
XY-XH2.5-4A21	4	7.5	12.5
XY-XH2.5-5A21	5	10.0	15.0
XY-XH2.5-6A21	6	12.5	17.5
XY-XH2.5-7A21	7	15.0	20.0
XY-XH2.5-8A21	8	17.5	22.5
XY-XH2.5-8A21	9	20.0	25.0
XY-XH2.5-9A21	10	22.5	27.5
XY-XH2.5-11A21	11	25.0	30.0
XY-XH2.5-12A21	12	27.5	32.5
XY-XH2.5-13A21	13	30.0	35.0
.....
XY-XH2.5-20A21	20	(20-1)*2.5	(20+1)*2.5



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED				
.X ± 0.35	X.* ± 5°	APR. Alex	TITLE: WAFER 2.54mm H7.0mm 90° DIP	
.XX ± 0.25	.X.* ± 3°	CHK. Jack	DWG NO. XY-XH2.54-NA21	
.XXX ± 0.15	.XX.* ± 1°	DRA. Can	PROJ. CUSTOMER DRAWING	
SIZE A4	SCALE 1:1	SHEET 1/1	REV. A	